

RKP203KN

Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G1304-0100 Rev.100 Dec 16, 2005

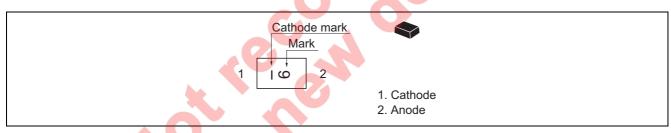
Features

- Adopting the trench structure improves low capacitance. (C = 0.31 pF max)
- Low forward resistance. (rf = $1.5 \Omega \text{ max}$)
- Low operation current.
- Ultra small leadless Package (0805type; the use of an undersurface electrode structure) for use in compact and products.

Ordering Information

| Type No. | Laser Mark | Package Name | Package Code (Previous Code) |
|----------|------------|--------------|---------------------------------|
| RKP203KN | 6 | MP8 | PXSN0002ZA-A |

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Value | Unit |
|----------------------|----------------|-------------|------|
| Reverse voltage | V_R | 30 | V |
| Forward current | I _F | 100 | mA |
| Power dissipation | Pd | 100 | mW |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

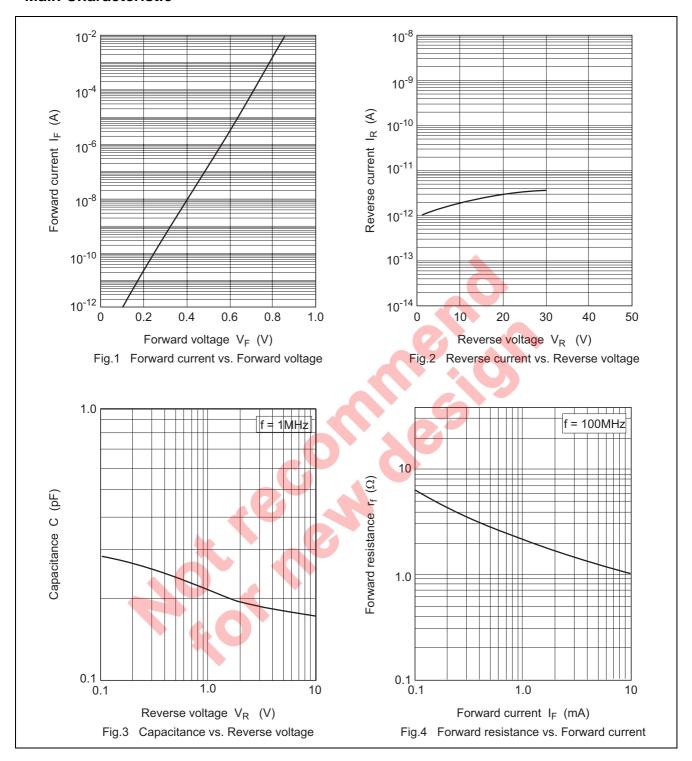
| Item | Symbol | Min | Тур | Max | Unit | Test Condition |
|--------------------|----------------|-----|-----|------|------|--|
| Reverse current | I _R | _ | _ | 100 | nA | V _R = 30 V |
| Forward voltage | V _F | _ | _ | 1.0 | V | I _F = 10 mA |
| Capacitance | С | _ | _ | 0.31 | pF | $V_R = 1 V$, $f = 1 MHz$ |
| Forward resistance | r _f | _ | _ | 2.5 | Ω | I _F = 2 mA, f = 100 MHz |
| | | _ | _ | 1.5 | | I _F = 10 mA, f = 100 MHz |
| ESD-Capability *1 | _ | 100 | _ | _ | V | $C = 200 \text{ pF}, RL = 0 \Omega$, Both forward |
| | | | | | | and reverse direction 1 pulse. |

Notes: 1. Failure criterion; $I_R > 100 \text{ nA}$ at $V_R = 30 \text{ V}$

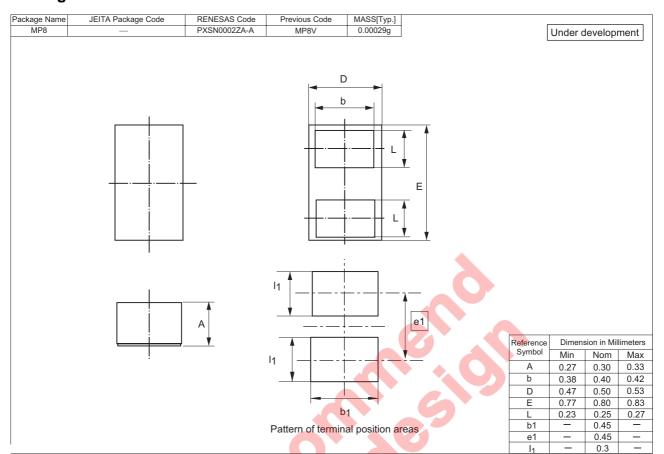
2. Please do not use the soldering iron due to avoid high stress to the MP8 package.



Main Characteristic



Package Dimensions



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